



CANEUS (<http://caneus.org>) and CNES CCT MCE (Microsystemes & Electronic Components (<http://cct/cct15/sommaire.htm>)) invite you to contribute to MNT Reliability workshop that will be held at Institut Aéronautique et Spatial (IAS), av E. Belin Toulouse, France, 29 & 30 May 2008

Workshop Topics

MEMS Reliability is a key challenge, especially for low volume and high reliability applications in various fields like Space, Aerospace, Defence, and Energy.

The goal of this workshop is to develop an MNT reliability and testing program with broad applicability for dealing with a diverse set of MNT systems and vendors for these systems.

The proposed consortium project will be based on a clear identification of the end-user reliability and radiation tolerance needs, and technical solutions to deal with MEMS design for reliability, virtual prototyping, technology analysis, failure analysis, test, qualification, and system versus component reliability trades.

The cross fertilization of inputs from end users, manufacturers, test, characterization and FA labs will trigger new opportunities for MEMS reliability activities.

Conclusions will emphasize a possible cooperation to be set up at a worldwide level and at the end of the two-day workshop; we hope to be in a position to provide answers for the following:

- Extent of the reliability and testing market for MNT systems and a list of competitors
- Build Consortia and funding proposal submission to be put together

Call for Project Participation

Paper/Presentations and Workshop Displays are solicited that address broad range of issues with reliability of Micro and Nano-devices and systems for use by the global aerospace industry.

We encourage you to submit abstracts of your paper that describe

- Best practice on MEMS reliability
 - o Reliability testing of Microsystems from academic and industrial resources
 - o Lessons learned to aerospace applications
 - o Applicable reliability standards in terms of Military Specifications and Space Applications Standards
- MEMS Package reliability:
 - o Novel packaging techniques for MNT systems,
 - o Harsh environment packaging
 - o Package characterization
- Radiation
 - o Space testing for harsh radiation
 - o Radiation tolerance, challenges with MNT reliability,
- End-user perspectives.
 - o Technical needs
 - o Economical constraints
 - o General strategy for space qualification of MNT
- Technical Challenges
 - o MEMS testing
 - o Survey / tutorial on MEMS reliability
 - o MEMS Failure Analysis process, tools and case studies
 - o MEMS design for reliability
- Existing clusters
 - o Open communities
 - o Consortium
 - o Database
- Other topics related to MEMS reliability are highly sought after and encouraged.

Abstract submissions of proposed paper/presentations and descriptions of display posters/demonstrations are due by March 28, 2008. Please email submissions to
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Key Submission and Notification dates

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| - Deadline for Abstract and Posters Submission: | March 28, 2008 |
| - Official Letters of Acceptance Sent: | April 4th, 2008 |
| - Final Manuscripts Due: | May 9, 2008 |